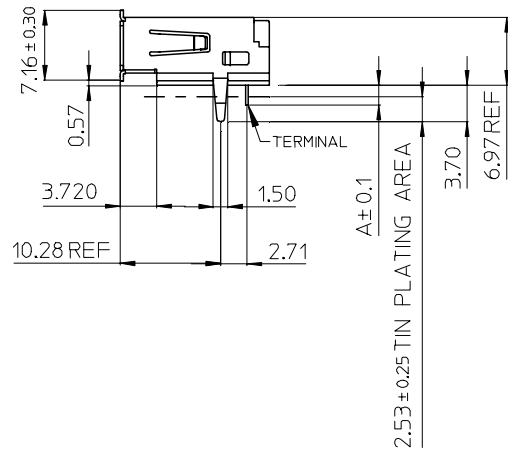
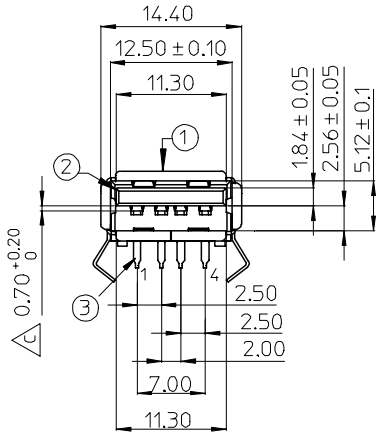


△ PCB LAYOUT (TOP VIEW)



NOTES:

1. MATERIAL:
 - ① METAL SHELL: COPPER ALLOY.
 - ② HOUSING: SEE CHART, 30% GLASS FIBER FILLED, UL94-V0.
 - ③ TERMINAL: PHOSPHOR BRONZE
2. TERMINAL:
 - CONTACT AREA: (a) GOLD FLASH.
 - (b) GOLD (Au), THICKNESS=30 MICROINCH MINIMUM.
 - SOLDER TAIL: TIN PLATED, THICKNESS=75 MICROINCH MINIMUM.
 - UNDER PLATED: NICKEL (Ni), THICKNESS=50 MICROINCH MINIMUM.
 - METAL SHELL: SEE CHART.
3. RECOMMENDED PCB THICKNESS: SEE CHART
4. PRODUCT SPECIFICATION: FOR IR REFER TO PS-67643-002
FOR NON IR REFER TO PS-67643-003
5. TORQUE FORCE SPEC: 2.50kg-cm Min. MEASURED AT BROKEN POINT.
6. TEST SUMMARY: FOR IR REFER TO TS-67643-002
FOR NON IR REFER TO TS-67643-003
7. PACKAGE: REFER TO PK-67643-002
8. LEAD FREE AND ROHS COMPLIANT PRODUCT

REVISE PCB LAYOUT VIEW EC NO: SH2007-0017 DRWN: ALL IN 2006/07/14 CHKD: 2006/07/14 APPR: WWSCHANG 2006/07/27	DESCRIPTION REV	QUALITY SYMBOLS ▽ = 0 △ = 0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 1:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.25 ± --- 1 PLACE ± 0.25 ± ---	mm INCH	DRAWN BY IVY-LIN	DATE 2005/03/31	TITLE USB A TYPE RCPT SINGLE RA THROUGH HOLE W/OFLG (LEAD-FREE VERSION)				
		ANGULAR ± 3 °		CHECKED BY ALL IN	DATE 2005/03/31	MOLEX INCORPORATED				
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		APPROVED BY WWSCHANG	DATE 2005/03/31	MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-67643-003	SHEET NO. 1 OF 2		

7 6 5 4 3 2 1

E

E

P/N	HOUSING MATERIAL	COLOR	CONTACT PLATING	METAL SHELL PLATING	REMARK
67643-0910	POLYESTER	BLACK	GOLD FLASH	IR REFLOW PROCESS TIN PLATED AT SOLDER AREA THICKNESS=100 MICROINCH MINIMUM UNDER PLATE:NICKEL (Ni),(SOLDERING AVAILABLE) SURFACE APPEARANCE:BRIGHT.	NON IR
67643-1910	POLYESTER	WHITE			REFLOW PROCESS
67643-2910	HIGH TEMPERATURE NYLON	BLACK			FOR IR
67643-3910	HIGH TEMPERATURE NYLON	WHITE			REFLOW PROCESS
67643-0911	POLYESTER	BLACK	GOLD PLATING 30 MICROINCH	NON IR REFLOW PROCESS: TIN PLATED. THICKNESS=80 MICROINCH MINIMUM UNDER PLATE:NICKEL (Ni). SURFACE APPEARANCE:BRIGHT.	NON IR
67643-1911	POLYESTER	WHITE			REFLOW PROCESS
67643-2911	HIGH TEMPERATURE NYLON	BLACK			FOR IR
67643-3911	HIGH TEMPERATURE NYLON	WHITE			REFLOW PROCESS
PCB THICKNESS		1.60±0.05			
DIMENSION "A"		2.60			

D

D

C

C

P/N	HOUSING MATERIAL	COLOR	CONTACT PLATING	METAL SHELL PLATING	REMARK
67643-0930	HIGH TEMPERATURE NYLON	BLACK	GOLD FLASH	FOR IR REFLOW PROCESS TIN PLATED AT SOLDER AREA THICKNESS=100 MICROINCH MINIMUM UNDER PLATE:NICKEL (Ni),(SOLDERING AVAILABLE) SURFACE APPEARANCE:BRIGHT.	FOR IR
67643-1930	HIGH TEMPERATURE NYLON	WHITE			REFLOW PROCESS
67643-0931	HIGH TEMPERATURE NYLON	BLACK	GOLD PLATING 30 MICROINCH		
67643-1931	HIGH TEMPERATURE NYLON	WHITE			
PCB THICKNESS		1.20±0.05			
DIMENSION "A"		2.00			

B

B

A

A

SEE SHEET 1 EC NO: SH2007-0017 DRWN: ALL IN CHKD: APPR: WWSCHANG 2006/07/14 2006/07/14 2006/07/27	DESCRIPTION REV	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	
		 	mm	INCH	DRAWN BY	DATE	TITLE USB A TYPE RCPT SINGLE RA THROUGH HOLE W/OFLG (LEAD-FREE VERSION)			
			4 PLACES ± ---	± ---	IVY-LIN	2005/03/31				
		 	mm	INCH	CHECKED BY	DATE	MOLEX INCORPORATED			
			3 PLACES ± ---	± ---	ALL IN	2005/03/31				
 	mm	INCH	APPROVED BY	DATE	MATERIAL NO.		DOCUMENT NO.	SHEET NO.		
	2 PLACES ± 0.25	± ---	WWSCHANG	2005/03/31	SEE TABLE		SD-67643-003			2 OF 2
			1 PLACE ± 0.25	± ---	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					
			ANGULAR ± 3 °							
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS							

6 5 4 3 2 1